

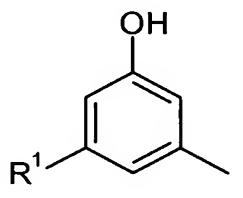
Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

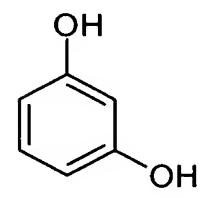
1. (Currently Amended) A two-component epoxy resin composition, wherein it comprises in the hardener component at least one Mannich base and after curing at a temperature between 5°C and 60°C has a glass transition temperature of more than 80°C.

80°C, wherein

the Mannich base is prepared using a phenolic compound of the formula (I) or (II)



(I)



(II)

with R¹ = H or CH₃,

and also formaldehyde and at least one polyamine.

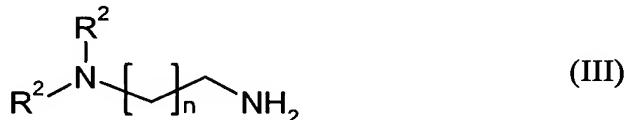
2. (Canceled)

3. (Previously Presented) The two-component epoxy resin composition as claimed in claim 1, wherein the Mannich base is prepared using a phenolic compound of the formula (I) with R¹ = H.

4. (Previously Presented) The two-component epoxy resin composition as claimed in claim 1, wherein, for the preparation of the Mannich base, in a first stage at least

one phenolic compound of the formula (I) or (II) is reacted with formaldehyde in the presence of a tertiary amine and in a subsequent stage reaction takes place with at least one polyamine.

5. (Previously Presented) The two-component epoxy resin composition as claimed in claim 4, wherein the tertiary amine has the formula (III)



with $\text{R}^2 = \text{C}_1\text{-C}_6$ alkyl and $\text{n} = 1, 2, \text{ or } 3$.

6. (Previously Presented) The two-component epoxy resin composition as claimed in claim 1, wherein the Mannich base contains not only secondary but also primary amino groups.

7. (Currently Amended) The two-component epoxy resin composition as claimed in claim 2, claim 1, wherein the polyamine is selected from the group consisting of 1,3-diaminopentane, isophoronediamine, 1,3- and 1,4-diaminocyclohexane, ~~1,2-diamino-~~ ~~cyclohexane~~ ~~1,2-diaminocyclohexane~~, 1,3- and 1,4-butanediamine, 1,3- and 1,5-pentanediamine, 1,5-diamino-2-methylpentane, 1,3-xylylenediamine, 1,3-bis(amino-methyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diaza-octamethylenediamine), tetraethylenepentamine, pentamethylenehexamine, dipropylenetriamine, tripropylenetetramine, tetrapropylenepentamine, 4,7-diaza-decamethylene-1,10-diamine, bis(4-aminocyclohexyl)methane, bis(4-amino-3-methylcyclohexyl)methane, 3(4),8(9)bis(aminomethyl)tricyclo[5.2.1.0^{2,6}]decane, and mixtures thereof.

8. (Currently Amended) The two-component epoxy resin composition as claimed in claim 2, claim 1, wherein the polyamine is selected from the group consisting of 1,3-xylylenediamine, 1,3-bis(aminomethyl)cyclohexane, diethylenetriamine, triethylenetetramine

(3,6-diazaoctamethylenediamine), tetraethylenepentamine, isophoronediamine, 1,2-diaminocyclohexane, 4,7-diaza-decamethylene-1,10-diamine, and mixtures thereof.

9. (Previously Presented) The two-component epoxy resin composition as claimed in claim 1, wherein curing takes place at a temperature between 10°C and 50°C, in particular between 10°C and 30°C.

10. (Previously Presented) The two-component epoxy resin composition as claimed in claim 1, wherein, after curing, the glass transition temperature is above 100°C, in particular between 100°C and 150°C.

11. (Previously Presented) The two-component epoxy resin composition as claimed in claim 1, wherein the two-component epoxy resin composition is an adhesive.

12. (Previously Presented) The two-component epoxy resin composition as claimed in claim 11, wherein the adhesive reinforces a structure.

13. (Previously Presented) The two-component epoxy resin composition as claimed in claim 12, wherein the adhesive bonds fiber-reinforced composites to built structures.

14. (Previously Presented) The two-component epoxy resin composition as claimed in claim 1, wherein the two-component epoxy resin composition is a polymeric matrix for producing fiber-reinforced composites.

15. (Withdrawn) A fiber-reinforced composite, wherein it is produced using a two-component epoxy resin composition as claimed in claim 1.

16. (Withdrawn) A method of adhesive bonding, wherein a two-component epoxy resin composition as claimed in claim 1 is mounted to at least one solid's surface and subsequently contacted with at least one further solid's surface.

17. (Previously Presented) A cured product obtained from a two-component epoxy resin composition as claimed in claim 1.

18. (Currently Amended) The two-component epoxy resin composition as claimed in claim 4, wherein the polyamine is selected from the group consisting of 1,3-diaminopentane, isophoronediamine, 1,3- and 1,4-diaminocyclohexane, 1,2-diaminocyclohexane, 1,2-diamino-cyclohexane, 1,3- and 1,4-butanediamine, 1,3- and 1,5-pantanediame, 1,5-diamino-2-methylpentane, 1,3-xylylenediamine, 1,3-bis(aminomethyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diaza-octamethylenediamine), tetraethylenepentamine, penta-methylenehexamine, dipropylenetriamine, tripropylenetetramine, tetrapropylenepentamine, 4,7-diaza-decamethylene-1,10-diamine, bis(4-aminocyclohexyl)methane, bis(4-amino-3-methylcyclohexyl)methane, 3(4),8(9)bis(aminomethyl)tricyclo[5.2.1.0^{2,6}]decane, and mixtures thereof.

19. (Previously Presented) The two-component epoxy resin composition as claimed in claim 4, wherein the polyamine is selected from the group consisting of 1,3-xylylenediamine, 1,3-bis(aminomethyl)cyclohexane, diethylenetriamine, triethylenetetramine (3,6-diazaoctamethylenediamine), tetraethylenepentamine, isophoronediamine, 1,2-diamino-cyclohexane, 4,7-diaza-decamethylene-1,10-diamine, and mixtures thereof.